

规格书编号

SPEC NO :

产品规格书

SPECIFICATION

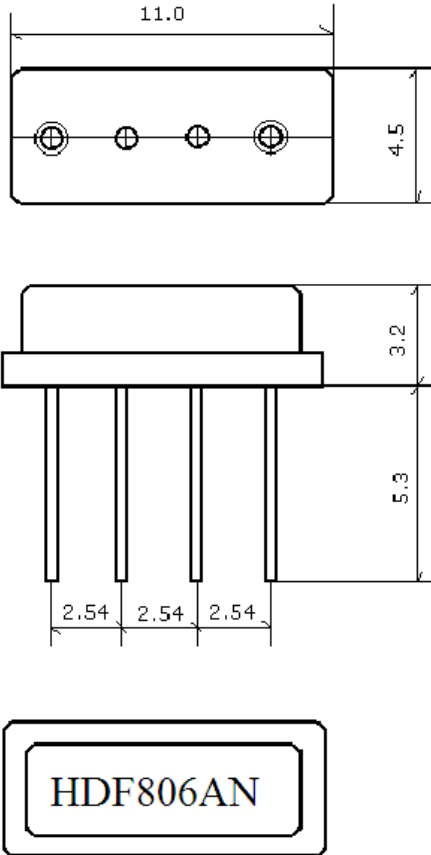
CUSTOMER 客户: _____
PRODUCT 产品: _____ SAW FILTER _____
MODEL NO 型号: _____ HDF806ANF11 _____
PREPARED 编制: _____ CHECKED 审核: _____
APPROVED 批准: _____ D A T E 日期: _____ 2006-5-11 _____

| | | |
|-------------------------|-------------|---------|
| 客户确认 CUSTOMER RECEIVED: | | |
| 审核 CHECKED | 批准 APPROVED | 日期 DATE |
| | | |

无锡市好达电子有限公司
Shoulder Electronics Limited

1. Package Dimension

Unit:mm



| NO | Function |
|----|----------|
| 1 | Input |
| 2 | Ground |
| 3 | Ground |
| 4 | Output |

2. Marking

2. Marking HD F806AN

- 2.1 Color: Black or Blue
- 2.2 806.: Center Frequency(MHz)

3.Performance

3.1Application

Low-Loss SAW Filter of cordless system.
Center Frequency:806 MHz

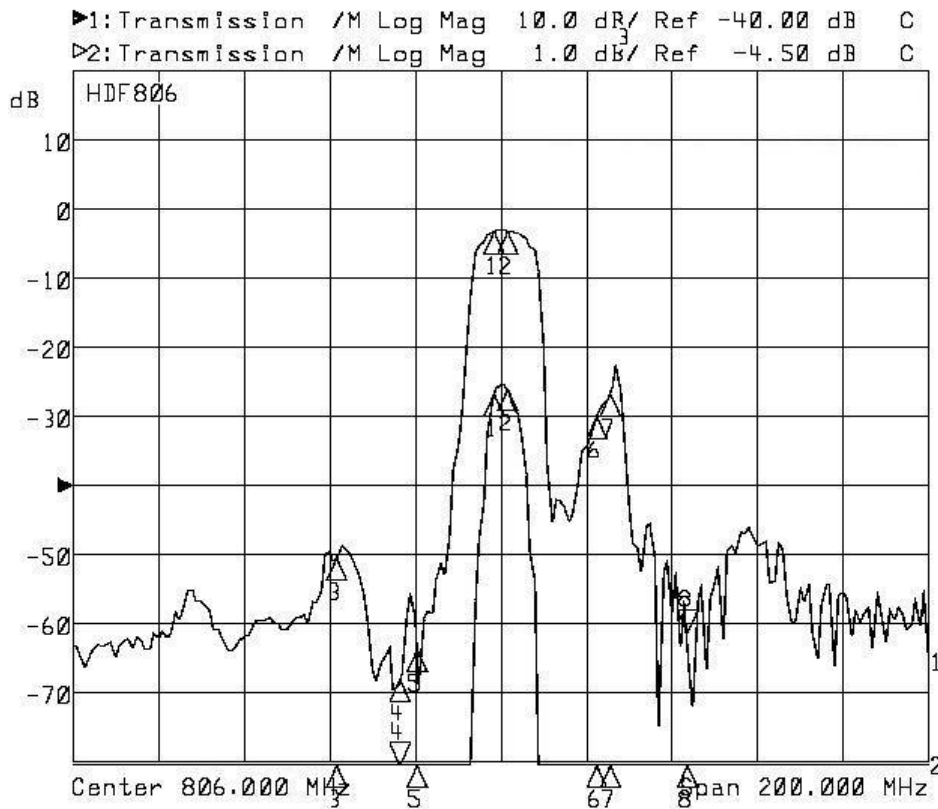
3.2Maximum Rating

| | |
|-----------------------------|----------------|
| Operation Temperature Range | -40°C to +85°C |
| Storage Temperature Range | -40°C to +85°C |
| DC. Voltage | 10 V max. |
| Maximum Input Power | 10dBm |

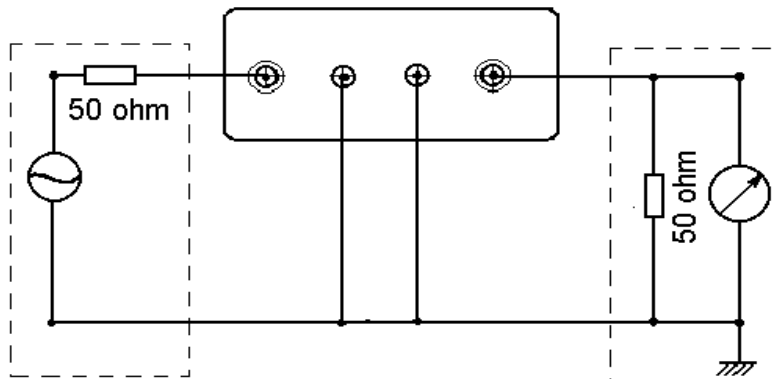
3.3 Electronic Characteristics

| Item | Frequency | Specification |
|---------------------------|----------------------------------|---------------|
| Center Frequency(f_0) | 806MHz | |
| Pass Band Width | $f_0 \pm 2\text{MHz}$ | |
| Insertion Loss | Passband | 4.5dB max. |
| Stop Band Rejection | $f_0 - 400 \sim -40.8\text{MHz}$ | 45dB min. |
| | $f_0 + 50 \sim +400\text{MHz}$ | 45dB min. |
| Terminating Impedance | | 50 Ω |

3.4 Frequency Characteristics



3.5 Test Circuit



4. ENVIRONMENTAL CHARACTERISTICS

4-1 High temperature exposure

Subject the device to +85°C for 16 hours. Then release the filter into the room conditions for 24 hours prior to the measurement. It shall fulfill the specifications in 3.3.

4-2 Low temperature exposure

Subject the device to -40°C for 16 hours. Then release the device into the room conditions for 24 hours prior to the measurement. It shall fulfill the specifications in 3.3.

4-3 Temperature cycling

Subject the device to a low temperature of -40°C for 30 minutes. Following by a high temperature of +85°C for 30 Minutes. Then release the device into the room conditions for 24 hours prior to the measurement. It shall meet the specifications in 3.3.

4-4 Resistance to solder heat

Dip the device terminals no closer than 1.5mm into the solder bath at 260°C \pm 10°C for 10 \pm 1 sec. Then release the device into the room conditions for 4 hours. The device shall meet the specifications in 3.3.

4-5 Solderability

Subject the device terminals into the solder bath at 245°C \pm 5°C for 5s, More than 95% area of the terminals must be covered with new solder. It shall meet the specifications in 3.3.

4-6 Mechanical shock

Drop the device randomly onto the concrete floor from the height of 1m 3 times. the device shall fulfill the specifications in 3.3.

4-7 Vibration

Subject the device to the vibration for 1 hour each in x,y and z axes with the amplitude of 1.5 mm at 10 to 55 Hz. The device shall fulfill the specifications in 3.3.

5. REMARK

5.1 Static voltage

Static voltage between signal load & ground may cause deterioration & destruction of the component. Please avoid static voltage.

5.2 Ultrasonic cleaning

Ultrasonic vibration may cause deterioration & destruction of the component. Please avoid ultrasonic cleaning

5.3 Soldering

Only leads of component may be soldered. Please avoid soldering another part of component.